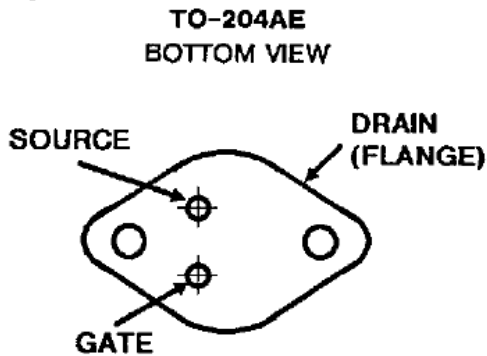


Package



Features

- -25A, -100V
- $r_{DS(on)} = 0.20\Omega$
- SOA is Power-Dissipation Limited
- Nanosecond Switching Speeds
- Linear Transfer Characteristics
- High Input Impedance
- Majority Carrier Device

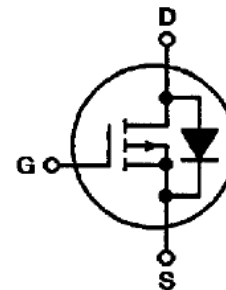
Description

The 2N6898 is a P-channel enhancement-mode silicon-gate power MOS field-effect transistor designed for applications such as switching regulators, switching converters, motor drivers, relay drivers, and drivers for high-power bipolar switching transistors requiring high speed and low gate-drive power. This device can be operated directly from an integrated circuit.

The 2N6898 is supplied in the JEDEC TO-204AE steel package.

Terminal Diagram

P-CHANNEL ENHANCEMENT MODE



Absolute Maximum Ratings ($T_C = +25^\circ\text{C}$) Unless Otherwise Specified

	2N6898	UNITS
Drain-Source Voltage	-100*	V
Drain-Gate Voltage ($R_{GS} = 1\text{M}\Omega$)	-100*	V
Continuous Drain Current		
RMS Continuous	-25*	A
Pulsed Drain Current	-60*	A
Gate-Source Voltage	$\pm 20^*$	V
Maximum Power Dissipation		
$T_C = +25^\circ\text{C}$	150*	W
Above $T_C = +25^\circ\text{C}$, Derate Linearly	1.2*	W/ $^\circ\text{C}$
Operating and Storage Junction Temperature Range	-55 to +150*	$^\circ\text{C}$
Maximum Lead Temperature for Soldering	260*	$^\circ\text{C}$
(At distances $\geq \frac{1}{8}$ " (3.17mm) from seating plane for 10s max)		

*JEDEC registered values



ELECTRICAL CHARACTERISTICS at Case Temperature (T_c) = 25°C unless otherwise specified.

CHARACTERISTIC	TEST CONDITIONS	LIMITS		UNITS
		Min.	Max.	
* Drain-Source Breakdown Voltage	BV _{DSS} I _D = 1 mA, V _{GS} = 0	-100	—	V
* Gate Threshold Voltage	V _{GS(th)} V _{GS} = V _{DS} , I _D = 0.25 mA	-2	-4	V
* Zero Gate Voltage Drain Current	I _{DSS} V _{DS} = -80 V	—	1	μA
	T _c = 125°C, V _{DS} = -80 V	—	50	
* Gate-Source Leakage Current	I _{GSS} V _{GS} = ±20 V, V _{DS} = 0	—	100	nA
* Drain-Source On Voltage	V _{DS(on)} ^a I _D = 15.8 A, V _{GS} = -10 V	—	3.16	V
	I _D = 25 A, V _{GS} = -10 V	—	-6	
* Static Drain-Source On Resistance	r _{DS(on)} ^a I _D = 15.8 A, V _{GS} = -10 V	—	0.2	Ω
	T _c = 125°C, I _D = 15.8 A, V _{GS} = 10 V	—	0.24	
* Forward Transconductance	g _{fs} ^a V _{DS} = -10 V, I _D = 15.8 A	4	16	mho
* Input Capacitance	C _{iss} V _{DS} = -25 V	—	3000	pF
* Output Capacitance	C _{oss} V _{GS} = 0 V	—	1500	
* Reverse Transfer Capacitance	C _{ras} f = 0.1 MHz	—	500	
* Turn-On Delay Time	t _{d(on)} V _{DS} = -50 V	—	50	ns
* Rise Time	t _r I _D = 12.5 A	—	250	
* Turn-Off Delay Time	t _{d(off)} R _{gen} = R _{gs} = 50 Ω	—	400	
* Fall Time	t _f V _{GS} = -10 V	—	250	
* Thermal Resistance Junction-to-Case	R _{θJC}	—	0.83	

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

CHARACTERISTIC	TEST CONDITIONS	LIMITS		UNITS
		Min.	Max.	
* Diode Forward Voltage	V _{SD} ^a I _{SD} = 25 A	0.8	1.6	V
* Reverse Recovery Time	t _{rr} I _F = 4 A, dI _F /dt = 100 A/μs	—	750	ns

*In accordance with JEDEC registration data.

^aPulsed: Pulse duration = 300 μs max., duty cycle = 2%

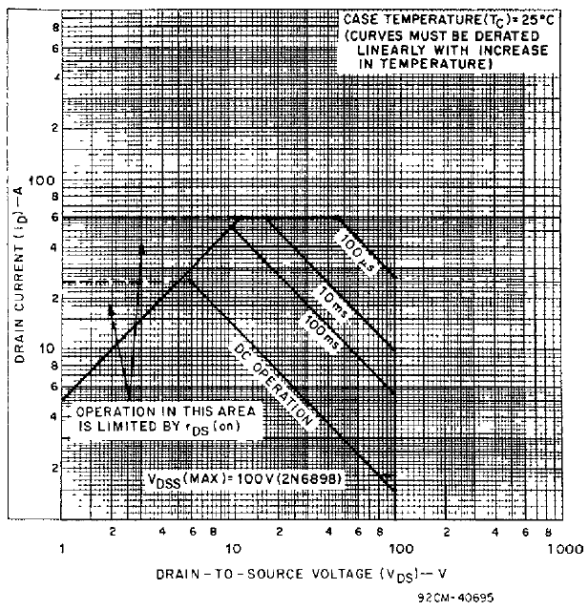


Fig. 1 - Maximum safe operating areas.



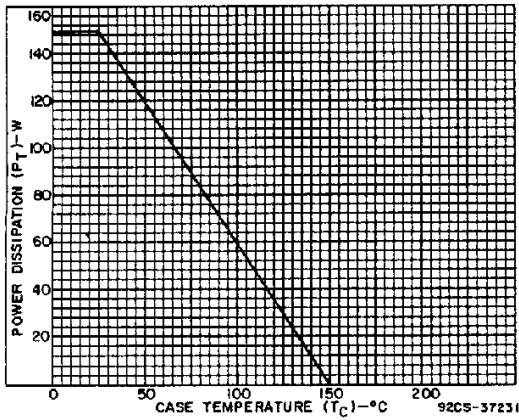


Fig. 2 - Power dissipation vs. temperature derating curve.

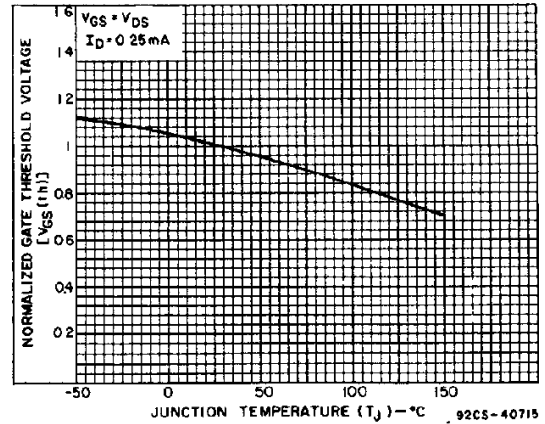


Fig. 3 - Typical normalized gate threshold voltage as a function of junction temperature.

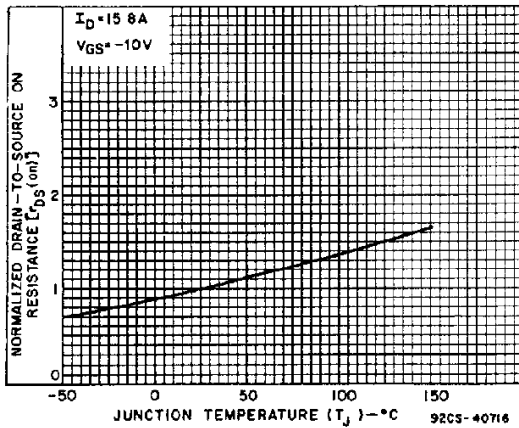


Fig. 4 - Typical normalized drain-to-source on resistance to junction temperature.

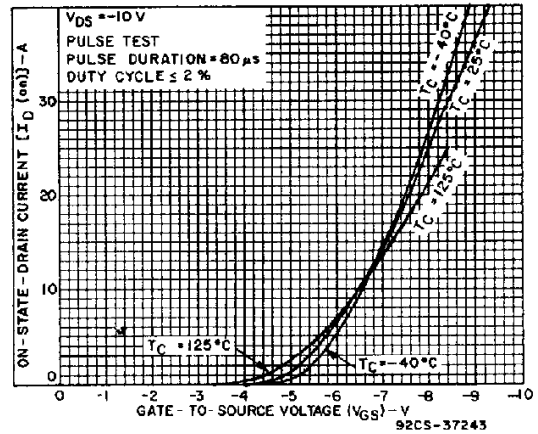


Fig. 5 - Typical transfer characteristics.

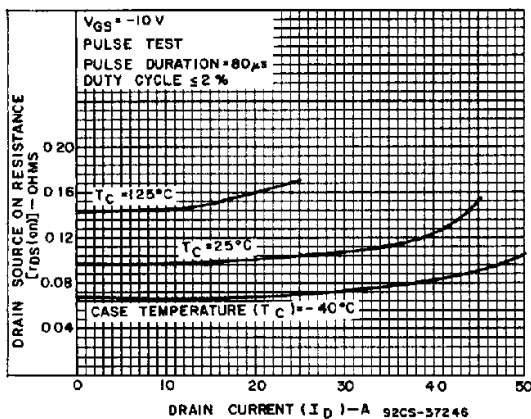


Fig. 6 - Typical drain-to-source on resistance as a function of drain current.

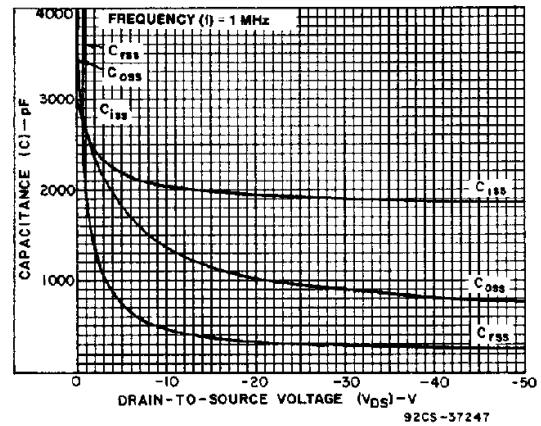


Fig. 7 - Capacitance as a function of drain-to-source voltage.



2N6898

P-Ch. Enhancement Mode Power MOS Field Effect Transistor

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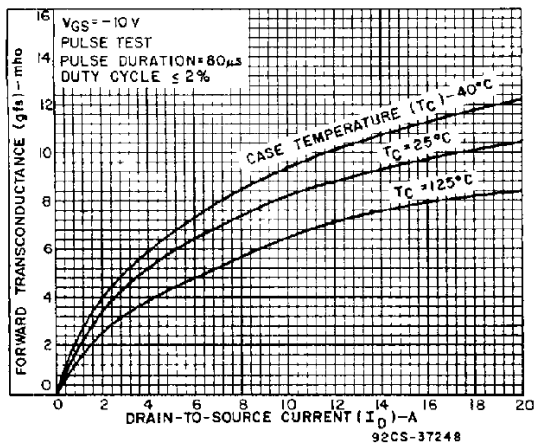


Fig. 8 - Typical forward transconductance as a function of drain current.

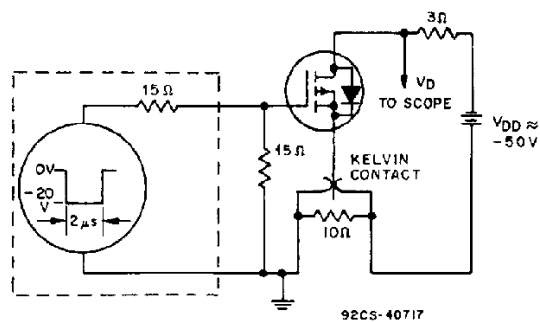


Fig. 9 - Switching time test circuit.

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